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**Elektronske komponente - Dolgoročno skladiščenje elektronskih polprevodniških elementov - 5. del: Elementi na čipih in rezinah (IEC 62435-5:2017)**

Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices (IEC 62435-5:2017)

**iTeh STANDARD PREVIEW**

Composants électroniques - Stockage de longue durée des dispositifs électroniques à semiconducteurs - Partie 5: Dispositifs de puces et plaquettes

[SIST EN 62435-5:2017](https://standards.iteh.ai/catalog/standards/sist/a421f610-d344-4894-bd90-4ba2572a5e66/sist-en-62435-5-2017)

**Ta slovenski standard je istoveten z: EN 62435-5:2017**

**ICS:**

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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**SIST EN 62435-5:2017****en**

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EUROPEAN STANDARD

EN 62435-5

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2017

ICS 31.020

English Version

## Electronic components - Long-term storage of electronic semiconductor devices - Part 5: Die and wafer devices (IEC 62435-5:2017)

Composants électroniques - Stockage de longue durée des dispositifs électroniques à semiconducteurs -  
Partie 5: Dispositifs de puces et plaquettes  
(IEC 62435-5:2017)

Elektronische Bauteile - Langzeitlagerung elektronischer Halbleiterbauelemente - Teil 5: Chip- und Wafererzeugnisse  
(IEC 62435-5:2017)

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SIST EN 62435-5:2017

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

**EN 62435-5:2017****European foreword**

The text of document 47/2328/FDIS, future edition 1 of IEC 62435-5, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62435-5:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-11-24
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-02-24

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IEC 60068-2-17	NOTE	Harmonized as EN 60068-2-17.
IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20.
IEC 60749-3	NOTE	Harmonized as EN 60749-3.
IEC 60749-20-1	NOTE	Harmonized as EN 60749-20-1.
IEC 60749-21	NOTE	Harmonized as EN 60749-21.
IEC 60749-22	NOTE	Harmonized as EN 60749-22.
IEC 61340-5-1	NOTE	Harmonized as EN 61340-5-1.
IEC 61340-2-1	NOTE	Harmonized as EN 61340-2-1.
IEC/TR 62258-3	NOTE	Harmonized as CLC/TR 62258-3.
IEC 62435-1	NOTE	Harmonized as EN 62435-1.

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62435-2	-	Electronic components - Long-term storage of electronic semiconductor devices - Part 2: Deterioration mechanisms	EN 62435-2	-

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IEC 62435-5

Edition 1.0 2017-01

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE

**Electronic components – Long-term storage of electronic semiconductor devices –  
Part 5: Die and wafer devices**

**Composants électroniques – Stockage de longue durée des dispositifs  
électroniques à semiconducteurs –  
Partie 5: Dispositifs de puces et plaquettes**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE  
OF ELECTRONIC SEMICONDUCTOR DEVICES –**
**Part 5: Die and wafer devices**

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International Standard IEC 62435-5 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2328/FDIS	47/2351/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62435 series, published under the general title *Electronic components – Long-term storage of electronic semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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